

Leadless NTC Thermistor Die intended for Wire Bonding



QUICK REFERENCE DATA		
PARAMETER	VALUE	UNIT
Resistance value at 25 °C	5063	Ω
Resistance value at 100 °C	493.3	Ω
Tolerance on R_{100} -value	± 5	%
$B_{25/85}$ -value	3435	K
Tolerance on $B_{25/85}$ -value	± 1	%
Operating temperature range	-55 to +175	°C
Response time (63.2 %) 25 °C to 85 °C still air (for info)	3	s
Dissipation factor δ in still air (for info, non-mounted die)	3	mW
Maximum power dissipation	50	mW
Weight	3	mg

MOUNTING

The thermistors are primarily intended for wire bonding. The parameters of the assembly process should be chosen in accordance with the lead-wire material.

The mounting process should be in compliance with the following guidelines and recommendations:

Die bonding:

- Gold electrode: silver epoxy gluing.
- Silver electrode: SAC reflow soldering - silver epoxy gluing - nano silver sintering.

Cleaning:

- Detergent spraying.
- Ultrasonic cleaning is strictly prohibited.

Wire bonding:

- The gold electrode has been tested for gold wire bonding with a wire diameter of 32 μm.

FEATURES

- Flat chip contacted top and bottom (Silver)
- Wide temperature range from -55 °C to +175 °C
- Specified at 100 °C for better temp. control
- Highly resistant to thermal shocks
- Ideal for wire bonding (aluminum or gold depending on metalization type)
- Delivered on blister tape
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

APPLICATIONS

- High temperature sensing, control and compensation.
E.g. IGBT modules (inverters in EV and HEV vehicles)
- IC and semiconductor protecting
- DC/AC power inverters and HIC overheat protecting

DESIGN-IN SUPPORT

For complete curve computation, please visit:

www.vishay.com/thermistors/ntc-curve-list/

MARKING

The thermistors have no marking and have electrode termination design without orientation.

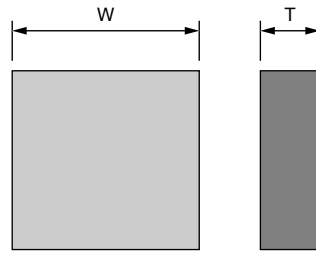
- The silver electrode has been tested for aluminum wire bonding with a wire diameter of 300 μm.

Encapsulation:

- In order to preserve the characteristics of the bonded die at long term an encapsulation is mandatory.
- The encapsulation is defined by the customer. Silicon and epoxy encapsulations have been tested. For recommendations on compatible encapsulants contact Vishay.

The behavior of the connected die is strongly depending on the particular processing and application conditions and we recommend to the users to test, verify and validate for themselves their particular application. Vishay will not endorse any responsibility of an abnormal behavior of components having been processed in non validated executions.

ELECTRICAL DATA AND ORDERING INFORMATION					
R_{25} (Ω)	R_{25} -TOL. (± %)	$B_{25/85}$ (K)	$B_{25/85}$ -TOL. (± %)	DESCRIPTION	SAP MATERIAL AND ORDERING NUMBER
5063	7.43	3435	1	Bare die with top / bottom silver termination	NTCC200E4C90008

DIMENSIONS in millimeters


Wire bondable surface

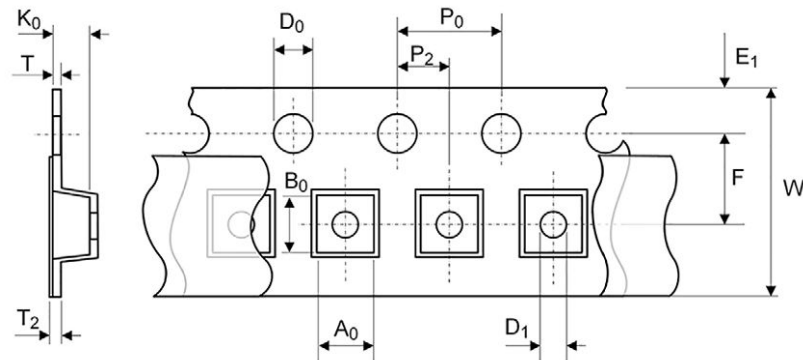
PARAMETER	VALUE
W	2 ± 0.1
T	0.7 max.

Note

- Non-dimensioned details do not affect the performance of the thermistors

PACKAGING INFORMATION

The components are delivered on 8 mm embossed blister tape (conductive polystyrene) conforming to EIA-481, with 2000 die per reel.



PARAMETER	VALUE
A ₀	2.2 ± 0.1
B ₀	2.2 ± 0.1
K ₀	1.0 ± 0.1
W	8 ± 0.3
F	3.5 ± 0.05
E ₁	1.75 ± 0.1
P ₀	4.0 ± 0.1
P ₂	2.0 ± 0.05
D ₀	1.5 ± 0.1
D ₁	1.0 ± 0.1
T	0.35 max.
T ₂	0.50 max.



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